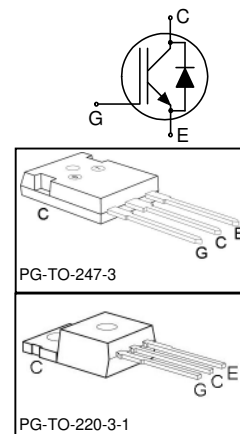


HighSpeed 2-Technology with soft, fast recovery anti-parallel Emitter Controlled HE diode

- **Designed for:**
  - SMPS
  - Lamp Ballast
  - ZVS-Converter
- **2<sup>nd</sup> generation HighSpeed-Technology for 1200V applications offers:**
  - loss reduction in resonant circuits
  - temperature stable behavior
  - parallel switching capability
  - tight parameter distribution
  - $E_{off}$  optimized for  $I_C = 3A$
- Qualified according to JEDEC<sup>2</sup> for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>



Type	$V_{CE}$	$I_C$	$E_{off}$	$T_j$	Marking	Package
IKW03N120H2	1200V	3A	0.15mJ	150°C	K03H1202	PG-TO-247-3
IKP03N120H2	1200V	3A	0.15mJ	150°C	K03H1202	PG-TO-220-3-1

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CE}$	1200	V
Triangular collector current	$I_C$	9.6	A
$T_C = 25^\circ\text{C}$ , $f = 140\text{kHz}$		3.9	
$T_C = 100^\circ\text{C}$ , $f = 140\text{kHz}$			
Pulsed collector current, $t_p$ limited by $T_{jmax}$	$I_{Cpuls}$	9.9	
Turn off safe operating area	-	9.9	
$V_{CE} \leq 1200\text{V}$ , $T_j \leq 150^\circ\text{C}$			
Diode forward current	$I_F$	9.6	
$T_C = 25^\circ\text{C}$		3.9	
$T_C = 100^\circ\text{C}$			
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Power dissipation	$P_{tot}$	62.5	W
$T_C = 25^\circ\text{C}$			
Operating junction and storage temperature	$T_j, T_{stg}$	-40...+150	°C
Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	

<sup>1</sup> J-STD-020 and JESD-022

### Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
<b>Characteristic</b>				
IGBT thermal resistance, junction – case	$R_{thJC}$		2.0	K/W
Diode thermal resistance, junction - case	$R_{thJCD}$		3.2	
Thermal resistance, junction – ambient	$R_{thJA}$	P-TO-220-3-1 P-TO-247-3-21	62	

### Electrical Characteristic, at $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=300\mu A$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=3A$ $T_j=25^\circ\text{C}$	-	2.2	2.8	
		$T_j=150^\circ\text{C}$ $V_{GE} = 10V, I_C=3A,$ $T_j=25^\circ\text{C}$	-	2.5	-	
Diode forward voltage	$V_F$	$V_{GE} = 0, I_F=2A$ $T_j=25^\circ\text{C}$	-	2.0	2.5	
		$T_j=150^\circ\text{C}$	-	1.75	-	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=90\mu A, V_{CE}=V_{GE}$	2.1	3	3.9	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=1200V, V_{GE}=0V$ $T_j=25^\circ\text{C}$	-	-	20	$\mu A$
		$T_j=150^\circ\text{C}$	-	-	80	
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=20V$	-	-	100	nA
Transconductance	$g_{fs}$	$V_{CE}=20V, I_C=3A$	-	2	-	S
<b>Dynamic Characteristic</b>						
Input capacitance	$C_{iss}$	$V_{CE}=25V,$ $V_{GE}=0V,$ $f=1\text{MHz}$	-	205	-	pF
Output capacitance	$C_{oss}$		-	24	-	
Reverse transfer capacitance	$C_{riss}$		-	7	-	
Gate charge	$Q_{Gate}$	$V_{CC}=960V, I_C=3A$ $V_{GE}=15V$	-	22	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$	PG-TO-220-3-1	-	7	-	nH
		PG-TO-247-3-21	-	13	-	

**Switching Characteristic, Inductive Load, at  $T_j=25\text{ }^\circ\text{C}$**

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=25\text{ }^\circ\text{C}$ , $V_{CC}=800\text{V}$ , $I_C=3\text{A}$ , $V_{GE}=15\text{V}/0\text{V}$ , $R_G=82\Omega$ , $L_\sigma^{(2)}=180\text{nH}$ , $C_\sigma^{(2)}=40\text{pF}$ Energy losses include "tail" and diode <sup>3)</sup> reverse recovery.	-	9.2	-	ns
Rise time	$t_r$		-	5.2	-	
Turn-off delay time	$t_{d(off)}$		-	281	-	
Fall time	$t_f$		-	29	-	
Turn-on energy	$E_{on}$		-	0.14	-	mJ
Turn-off energy	$E_{off}$		-	0.15	-	
Total switching energy	$E_{ts}$		-	0.29	-	
<b>Anti-Parallel Diode Characteristic</b>						
Diode reverse recovery time	$t_{rr}$	$T_j=25\text{ }^\circ\text{C}$ , $V_R=800\text{V}$ , $I_F=3\text{A}$ , $R_G=82\Omega$	-	42	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	0.23	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	10.3	-	A
Diode current slope	$di_F/dt$		-	993	-	A/ $\mu\text{s}$
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	1180	-	

**Switching Characteristic, Inductive Load, at  $T_j=150\text{ }^\circ\text{C}$**

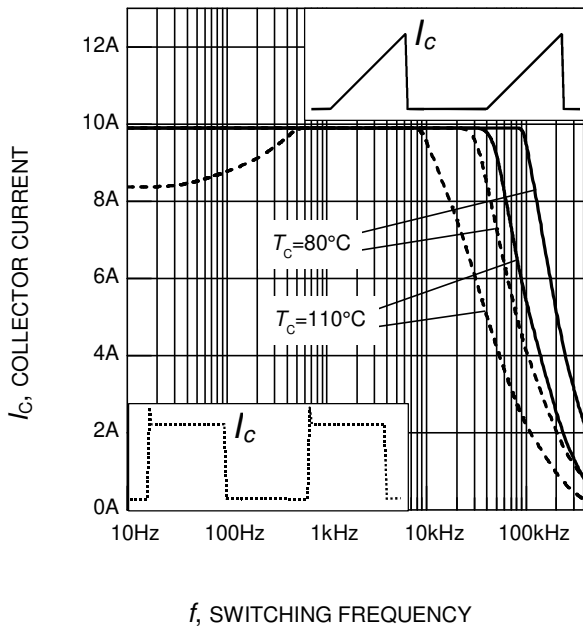
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=150\text{ }^\circ\text{C}$ $V_{CC}=800\text{V}$ , $I_C=3\text{A}$ , $V_{GE}=15\text{V}/0\text{V}$ , $R_G=82\Omega$ , $L_\sigma^{(2)}=180\text{nH}$ , $C_\sigma^{(2)}=40\text{pF}$ Energy losses include "tail" and diode <sup>3)</sup> reverse recovery.	-	9.4	-	ns
Rise time	$t_r$		-	6.7	-	
Turn-off delay time	$t_{d(off)}$		-	340	-	
Fall time	$t_f$		-	63	-	
Turn-on energy	$E_{on}$		-	0.22	-	mJ
Turn-off energy	$E_{off}$		-	0.26	-	
Total switching energy	$E_{ts}$		-	0.48	-	
<b>Anti-Parallel Diode Characteristic</b>						
Diode reverse recovery time	$t_{rr}$	$T_j=150\text{ }^\circ\text{C}$ $V_R=800\text{V}$ , $I_F=3\text{A}$ , $R_G=82\Omega$	-	125	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	0.51	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	12	-	A
Diode current slope	$di_F/dt$		-	829	-	A/ $\mu\text{s}$
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	540	-	

<sup>2)</sup> Leakage inductance  $L_\sigma$  and stray capacity  $C_\sigma$  due to dynamic test circuit in figure E

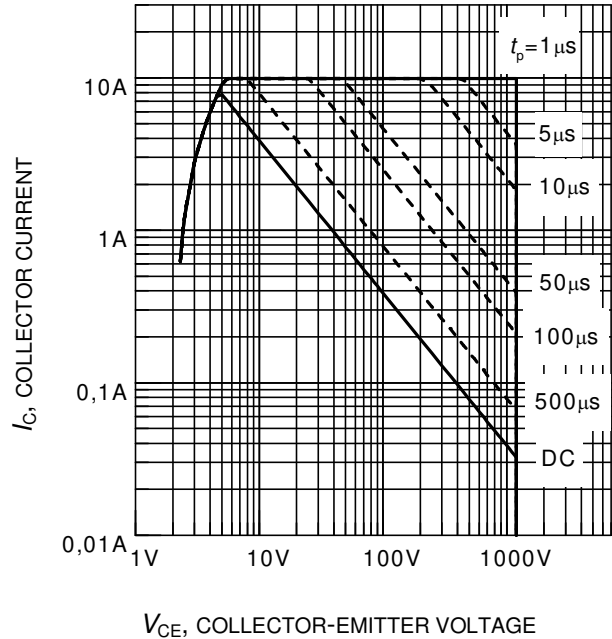
<sup>3)</sup> Commutation diode from device IKP03N120H2

**Switching Energy ZVT, Inductive Load**

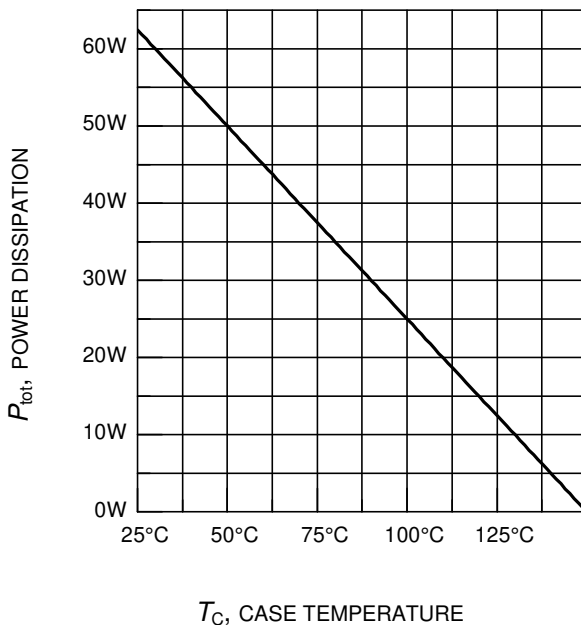
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic</b>						
Turn-off energy	$E_{off}$	$V_{CC}=800V,$ $I_C=3A,$ $V_{GE}=15V/0V,$ $R_G=82\Omega,$ $C_r^{(2)}=4nF$ $T_j=25^\circ C$ $T_j=150^\circ C$	-	0.05	-	mJ
			-	0.09	-	



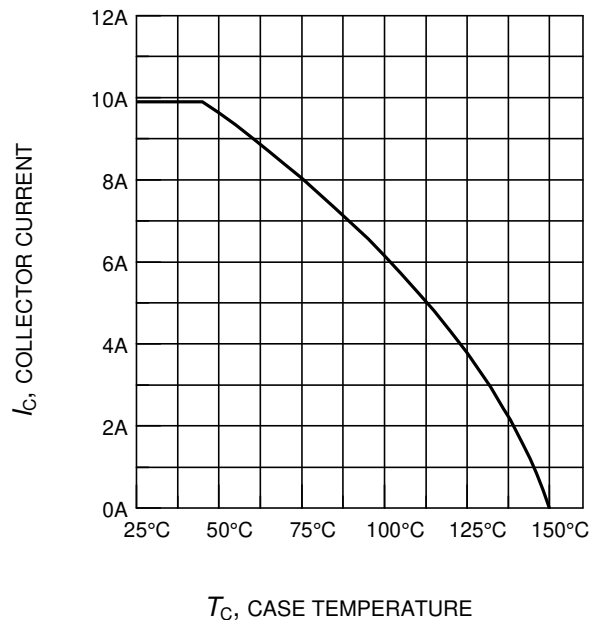
**Figure 1. Collector current as a function of switching frequency**  
( $T_j \leq 150^\circ\text{C}$ ,  $D = 0.5$ ,  $V_{CE} = 800\text{V}$ ,  $V_{GE} = +15\text{V}/0\text{V}$ ,  $R_G = 82\Omega$ )



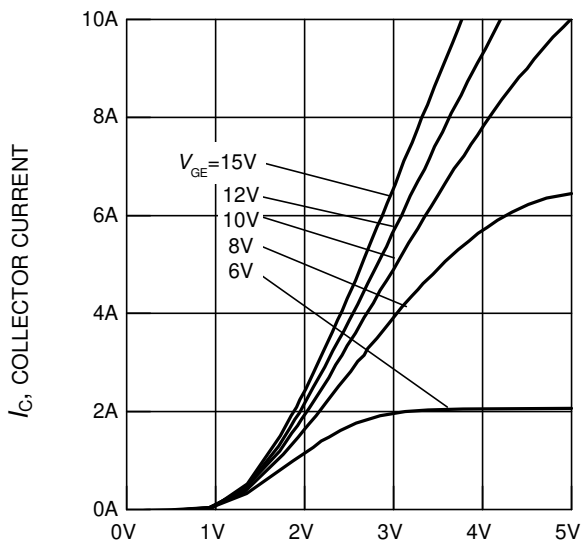
**Figure 2. Safe operating area**  
( $D = 0$ ,  $T_C = 25^\circ\text{C}$ ,  $T_j \leq 150^\circ\text{C}$ )



**Figure 3. Power dissipation as a function of case temperature**  
( $T_j \leq 150^\circ\text{C}$ )

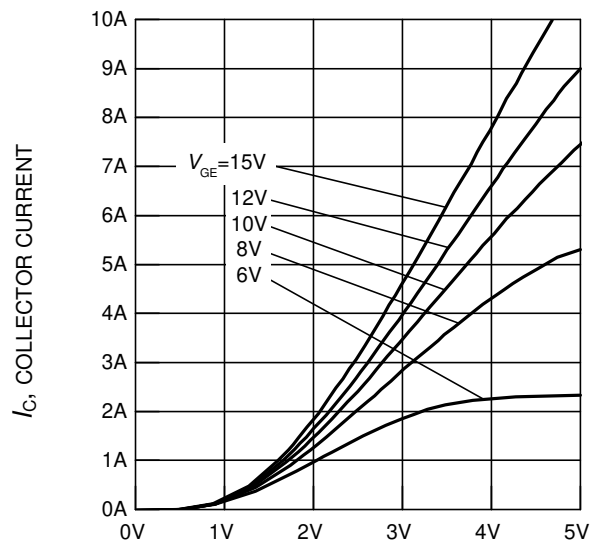


**Figure 4. Collector current as a function of case temperature**  
( $V_{GE} \leq 15\text{V}$ ,  $T_j \leq 150^\circ\text{C}$ )



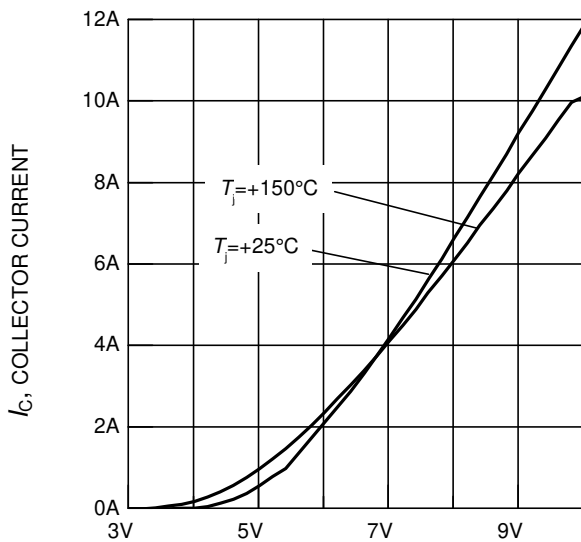
$V_{CE}$ , COLLECTOR-EMITTER VOLTAGE

**Figure 5. Typical output characteristics**  
( $T_j = 25^\circ\text{C}$ )



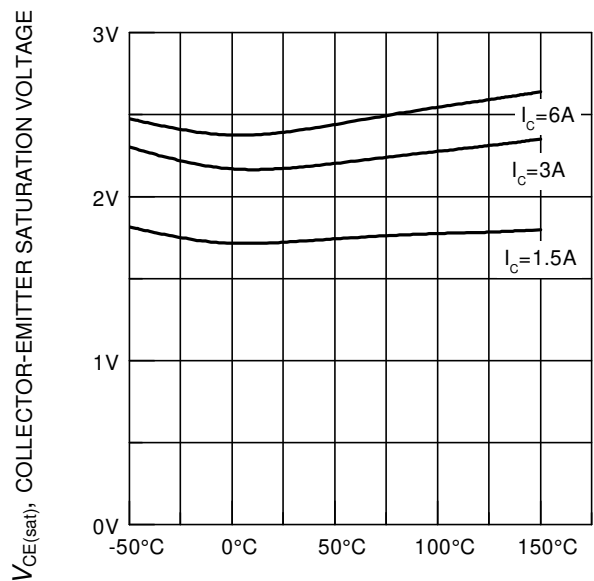
$V_{CE}$ , COLLECTOR-EMITTER VOLTAGE

**Figure 6. Typical output characteristics**  
( $T_j = 150^\circ\text{C}$ )



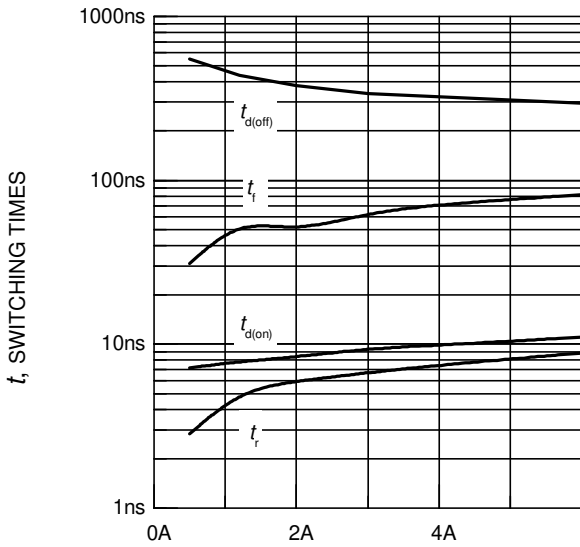
$V_{GE}$ , GATE-EMITTER VOLTAGE

**Figure 7. Typical transfer characteristics**  
( $V_{CE} = 20\text{V}$ )



$T_j$ , JUNCTION TEMPERATURE

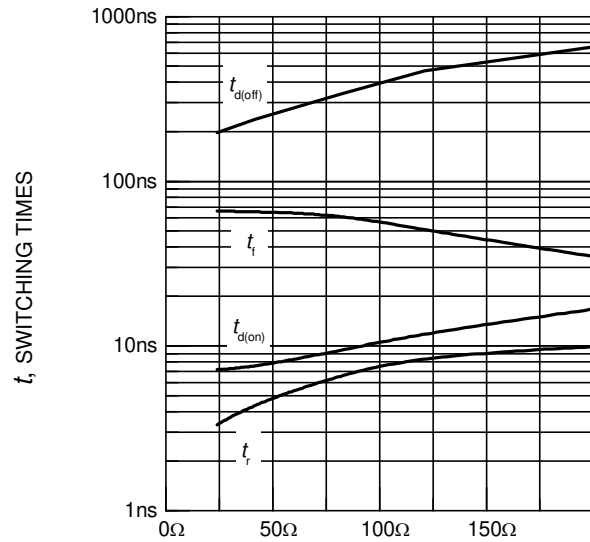
**Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature**  
( $V_{GE} = 15\text{V}$ )



$I_C$ , COLLECTOR CURRENT

**Figure 9. Typical switching times as a function of collector current**

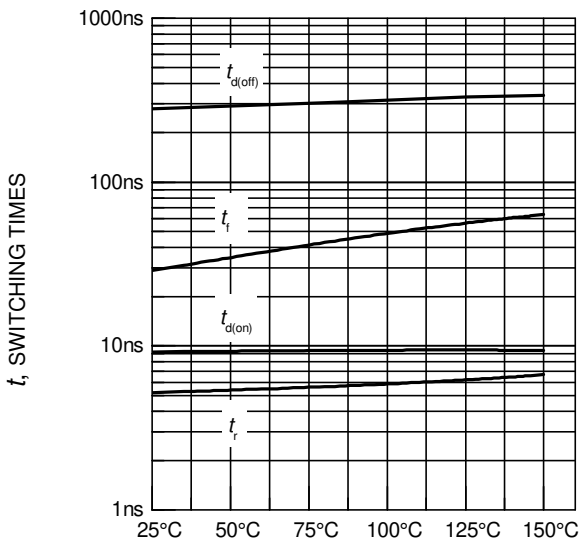
(inductive load,  $T_j = 150^\circ\text{C}$ ,  
 $V_{CE} = 800\text{V}$ ,  $V_{GE} = +15\text{V}/0\text{V}$ ,  $R_G = 82\Omega$ ,  
dynamic test circuit in Fig.E)



$R_G$ , GATE RESISTOR

**Figure 10. Typical switching times as a function of gate resistor**

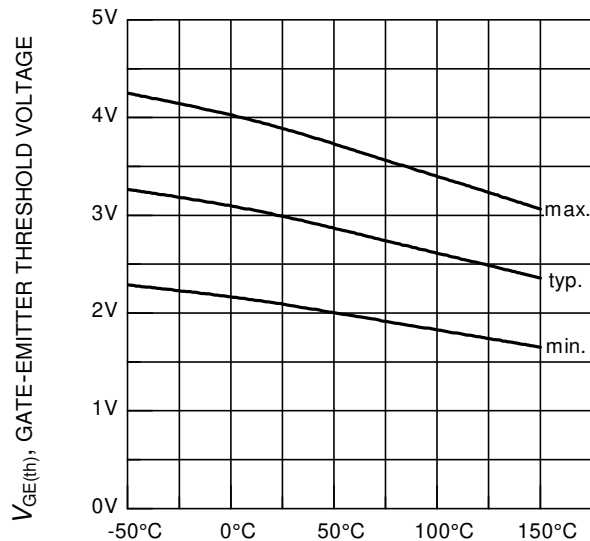
(inductive load,  $T_j = 150^\circ\text{C}$ ,  
 $V_{CE} = 800\text{V}$ ,  $V_{GE} = +15\text{V}/0\text{V}$ ,  $I_C = 3\text{A}$ ,  
dynamic test circuit in Fig.E)



$T_j$ , JUNCTION TEMPERATURE

**Figure 11. Typical switching times as a function of junction temperature**

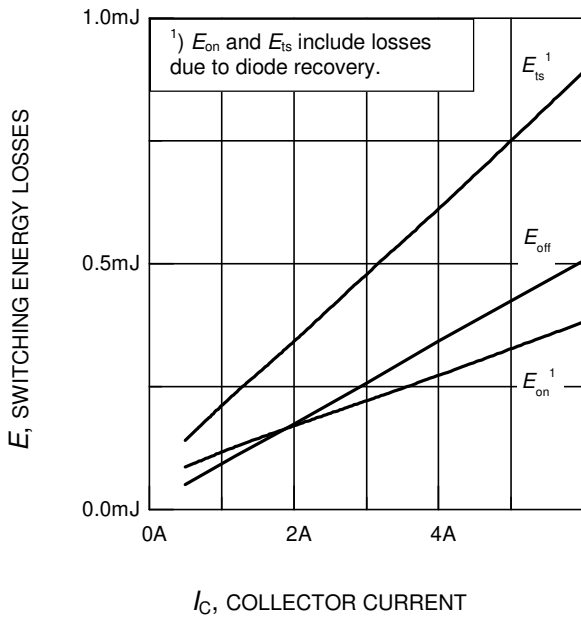
(inductive load,  $V_{CE} = 800\text{V}$ ,  
 $V_{GE} = +15\text{V}/0\text{V}$ ,  $I_C = 3\text{A}$ ,  $R_G = 82\Omega$ ,  
dynamic test circuit in Fig.E)



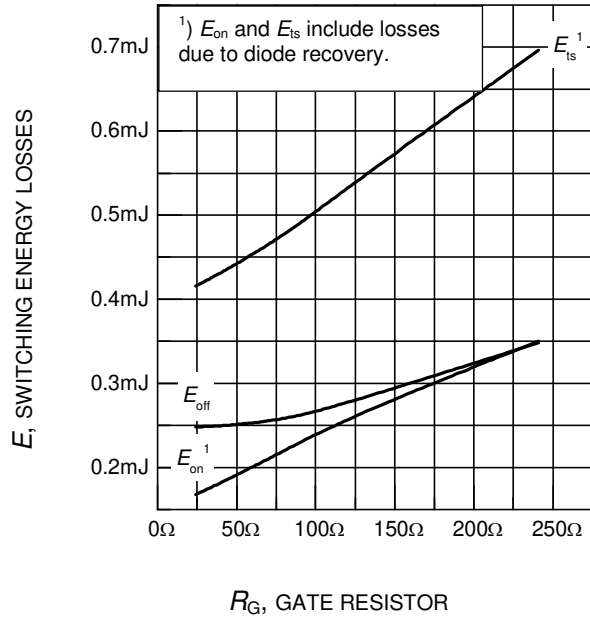
$T_j$ , JUNCTION TEMPERATURE

**Figure 12. Gate-emitter threshold voltage as a function of junction temperature**

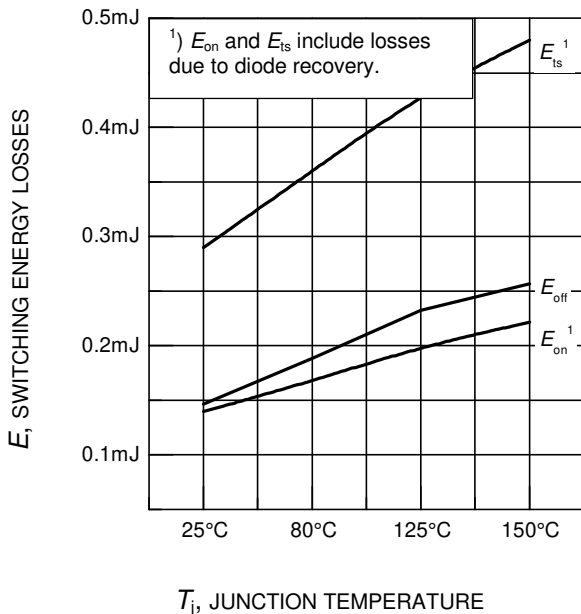
( $I_C = 0.09\text{mA}$ )



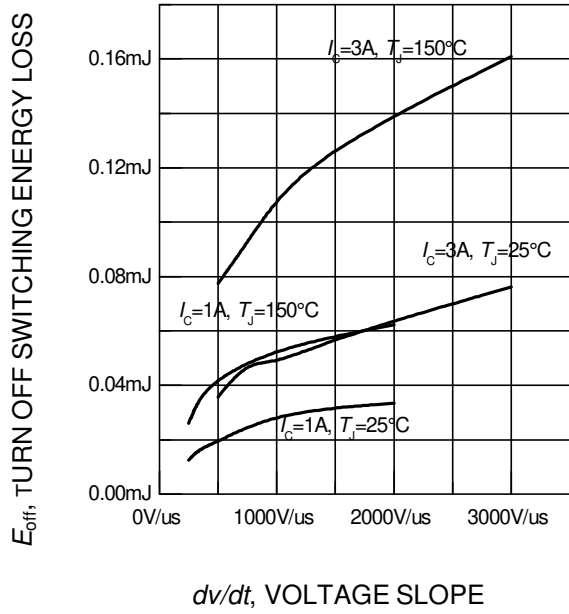
**Figure 13. Typical switching energy losses as a function of collector current**  
(inductive load,  $T_j = 150^\circ\text{C}$ ,  $V_{CE} = 800\text{V}$ ,  $V_{GE} = +15\text{V}/0\text{V}$ ,  $R_G = 82\Omega$ , dynamic test circuit in Fig.E )



**Figure 14. Typical switching energy losses as a function of gate resistor**  
(inductive load,  $T_j = 150^\circ\text{C}$ ,  $V_{CE} = 800\text{V}$ ,  $V_{GE} = +15\text{V}/0\text{V}$ ,  $I_C = 3\text{A}$ , dynamic test circuit in Fig.E )

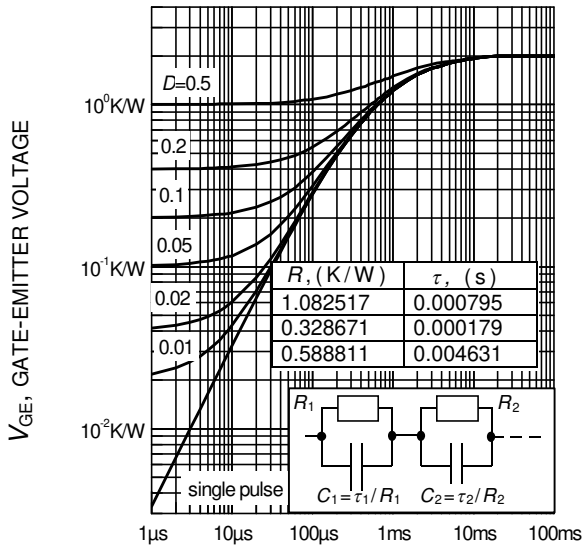


**Figure 15. Typical switching energy losses as a function of junction temperature**  
(inductive load,  $V_{CE} = 800\text{V}$ ,  $V_{GE} = +15\text{V}/0\text{V}$ ,  $I_C = 3\text{A}$ ,  $R_G = 82\Omega$ , dynamic test circuit in Fig.E )

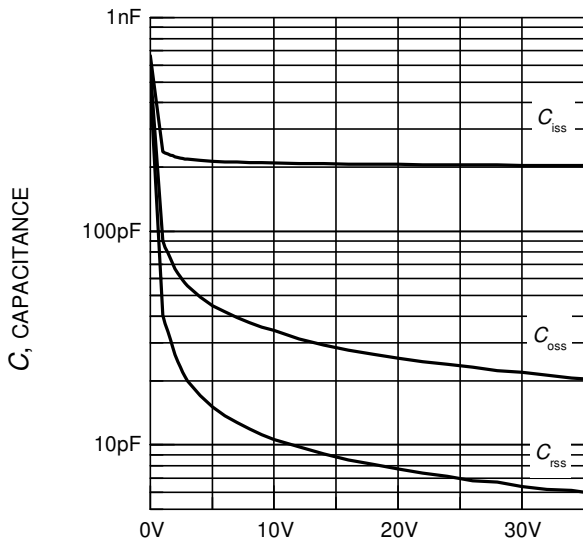


**Figure 16. Typical turn off switching energy loss for soft switching**  
(dynamic test circuit in Fig. E)

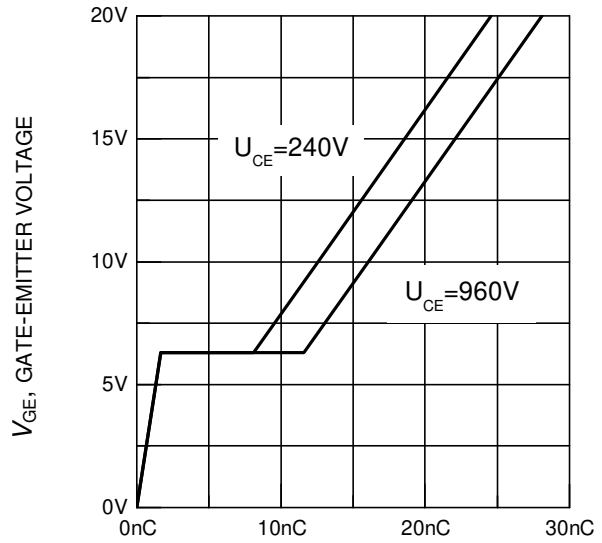




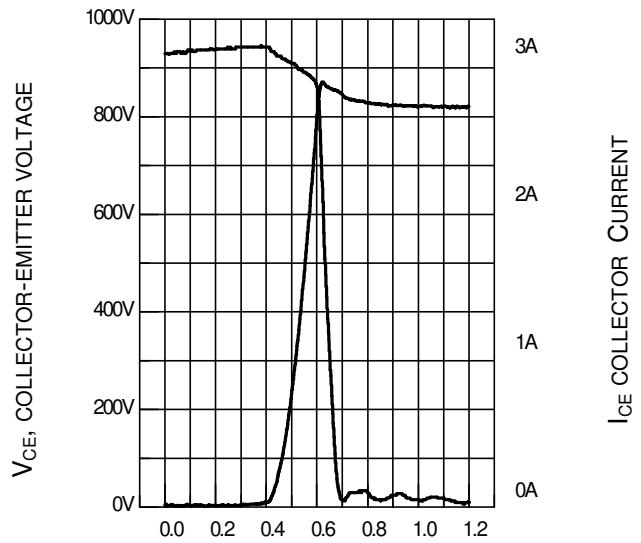
$Q_{GE}$ , GATE CHARGE  
**Figure 17. Typical gate charge**  
( $I_C = 3A$ )



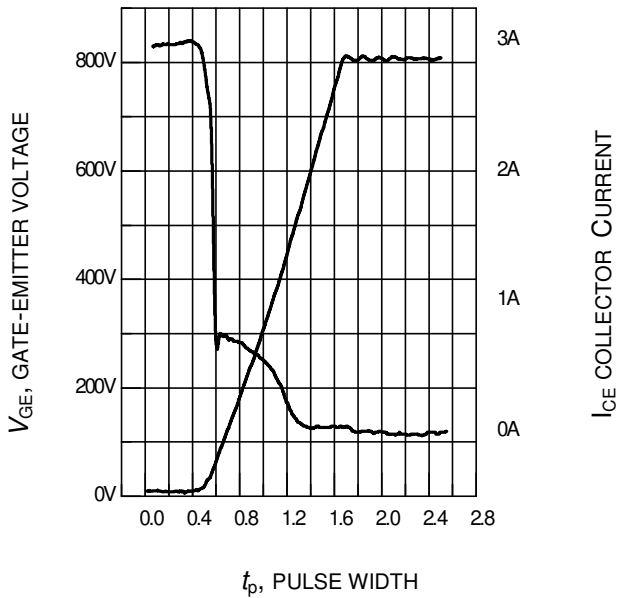
$V_{CE}$ , COLLECTOR-EMITTER VOLTAGE  
**Figure 18. Typical capacitance as a function of collector-emitter voltage**  
( $V_{GE} = 0V$ ,  $f = 1MHz$ )



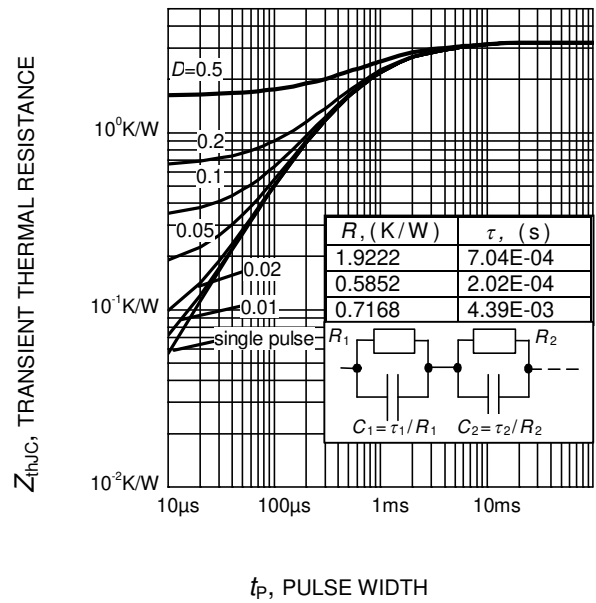
$Q_{GE}$ , GATE CHARGE  
**Figure 19. Typical turn on behavior**  
( $I_C = 3A$ )



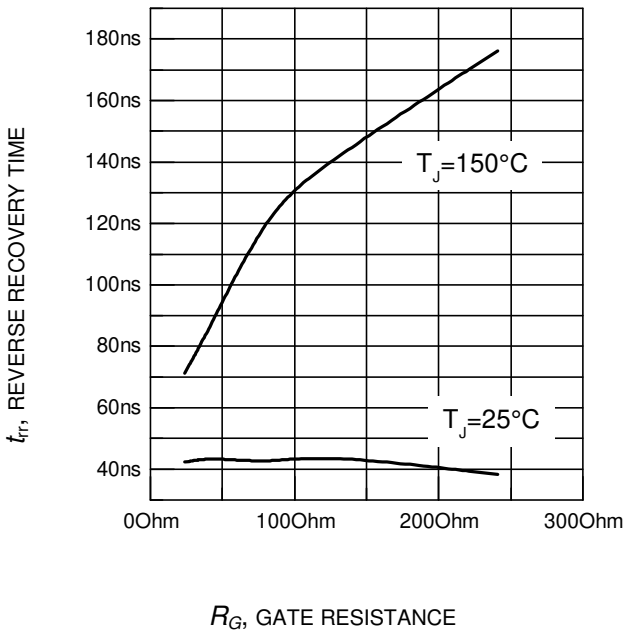
$t_p$ , PULSE WIDTH  
**Figure 20. Typical turn off behavior, hard switching**  
( $V_{GE} = 15/0V$ ,  $R_G = 82\Omega$ ,  $T_j = 150^\circ C$ ,  
Dynamic test circuit in Figure E)



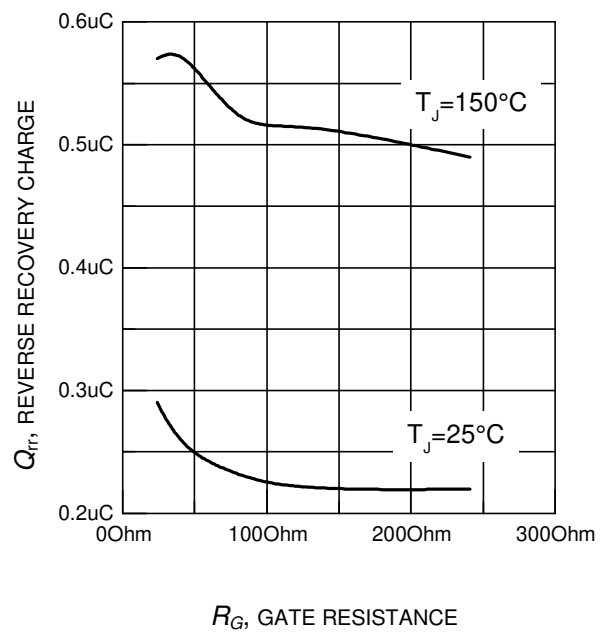
**Figure 21. Typical turn off behavior, soft switching**  
( $V_{GE}=15/0V$ ,  $R_G=82\Omega$ ,  $T_j = 150^\circ C$ ,  
Dynamic test circuit in Figure E)



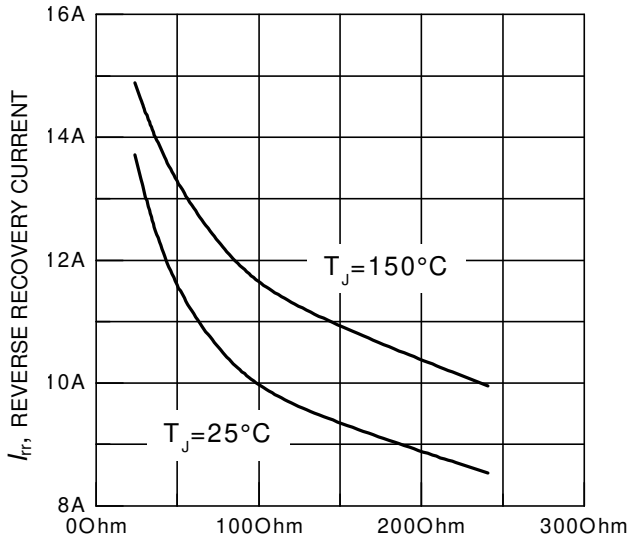
**Figure 22. Diode transient thermal impedance as a function of pulse width**  
( $D=t_p/T$ )



**Figure 23. Typical reverse recovery time as a function of diode current slope**  
 $V_R=800V$ ,  $I_F=3A$ ,  
Dynamic test circuit in Figure E)

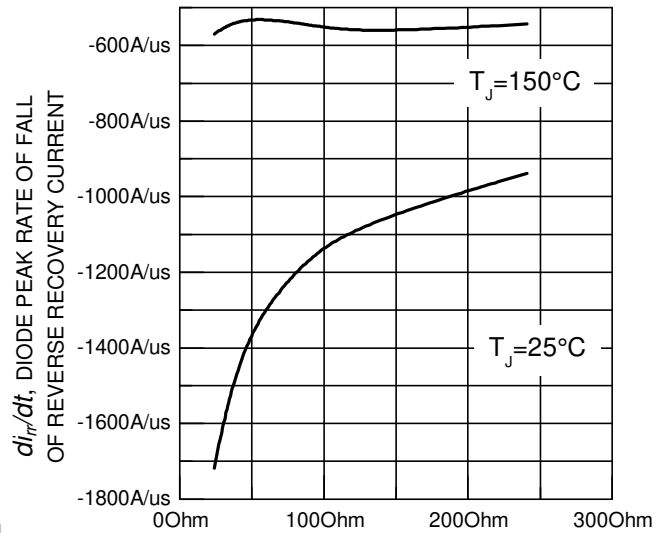


**Figure 24. Typical reverse recovery charge as a function of diode current slope**  
( $V_R=800V$ ,  $I_F=3A$ ,  
Dynamic test circuit in Figure E)



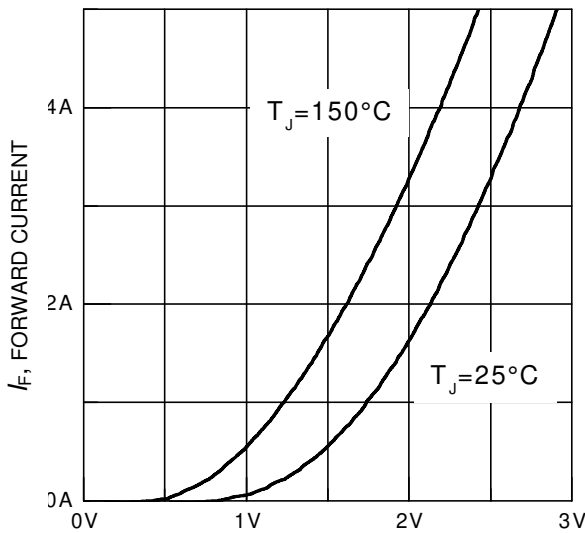
$R_G$ , GATE RESISTANCE

**Figure 25. Typical reverse recovery current as a function of diode current slope**  
( $V_R=800V$ ,  $I_F=3A$ ,  
Dynamic test circuit in Figure E)



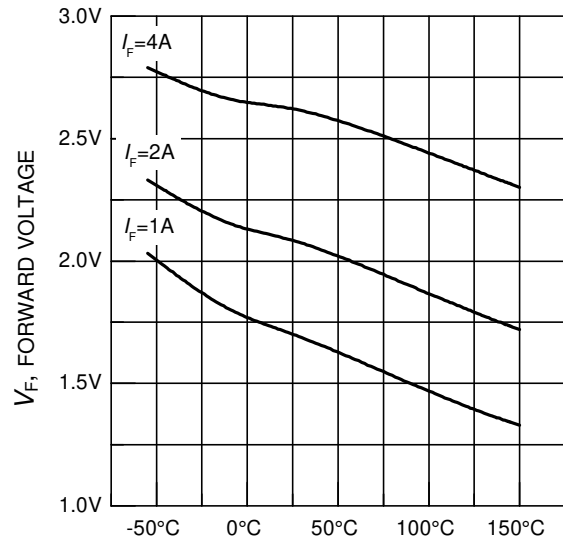
$R_G$ , GATE RESISTANCE

**Figure 26. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope**  
( $V_R=800V$ ,  $I_F=3A$ ,  
Dynamic test circuit in Figure E)



$V_F$ , FORWARD VOLTAGE

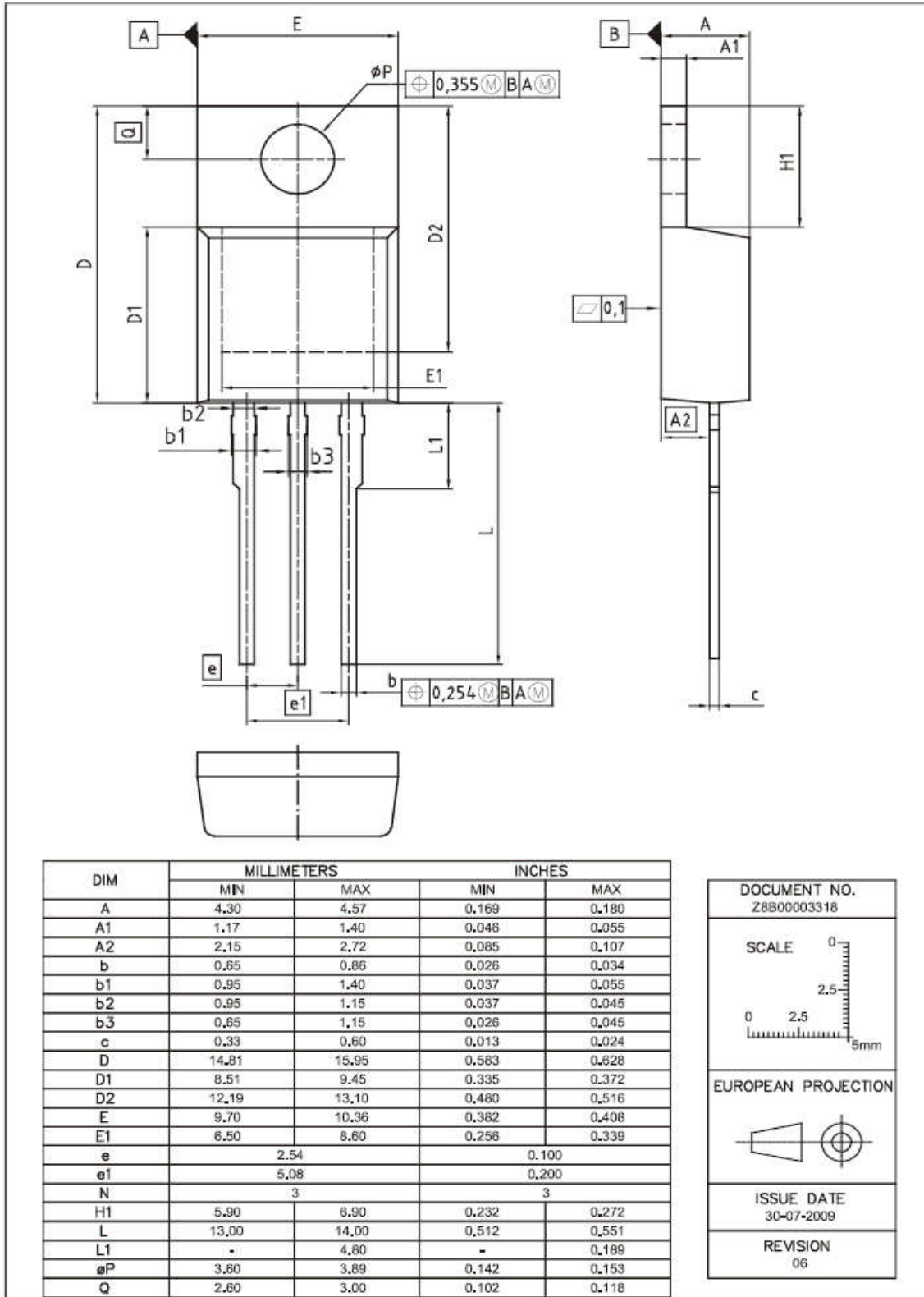
**Figure 27. Typical diode forward current as a function of forward voltage**



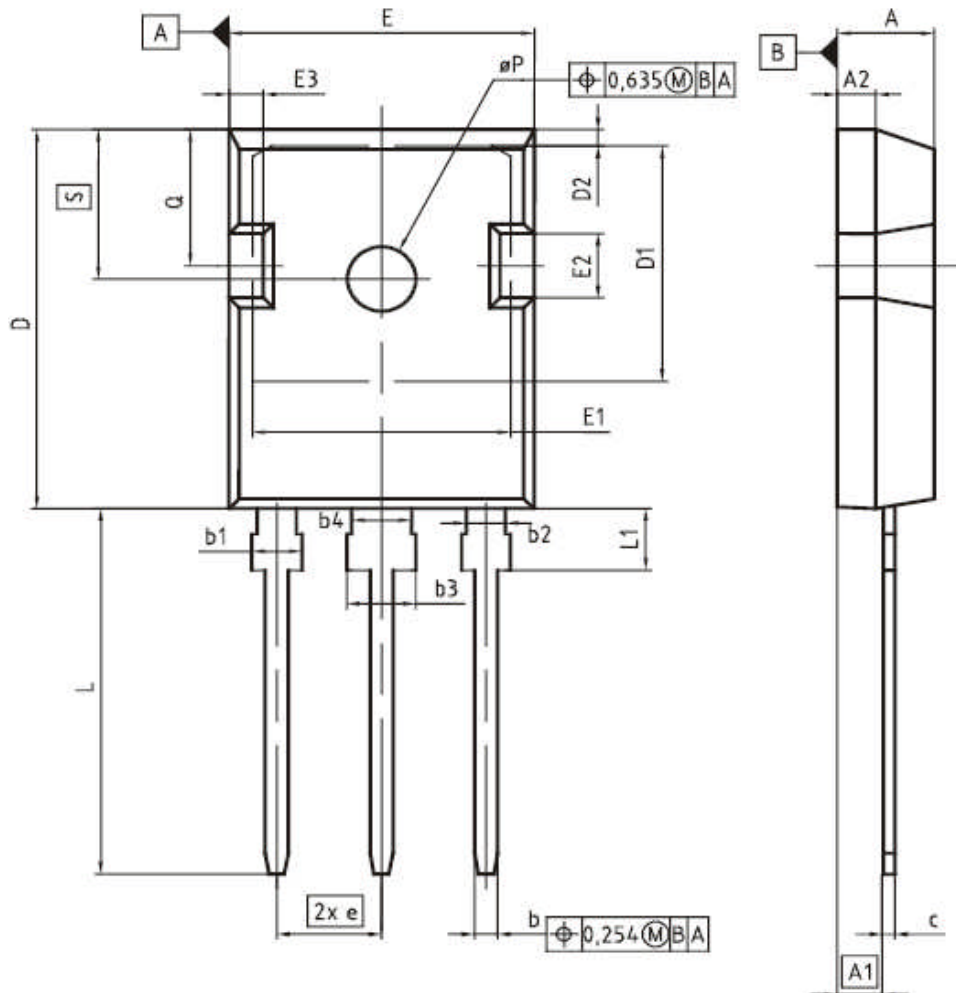
$T_J$ , JUNCTION TEMPERATURE

**Figure 28. Typical diode forward voltage as a function of junction temperature**

PG-TO220-3



PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4,83	5,21	0,190	0,205
A1	2,27	2,54	0,089	0,100
A2	1,85	2,16	0,073	0,085
b	1,07	1,33	0,042	0,052
b1	1,90	2,41	0,075	0,095
b2	1,90	2,16	0,075	0,085
b3	2,87	3,38	0,113	0,133
b4	2,87	3,13	0,113	0,123
c	0,55	0,68	0,022	0,027
D	20,80	21,10	0,819	0,831
D1	16,25	17,85	0,640	0,695
D2	0,95	1,35	0,037	0,053
E	15,70	16,13	0,618	0,635
E1	13,10	14,15	0,516	0,557
E2	3,68	5,10	0,145	0,201
E3	1,00	2,60	0,039	0,102
e	5,44 (BSC)		0,214 (BSC)	
N	3		3	
L	19,80	20,32	0,780	0,800
L1	4,10	4,47	0,161	0,176
$\phi P$	3,50	3,70	0,138	0,146
Q	5,49	6,00	0,216	0,236
S	6,04	6,30	0,238	0,248

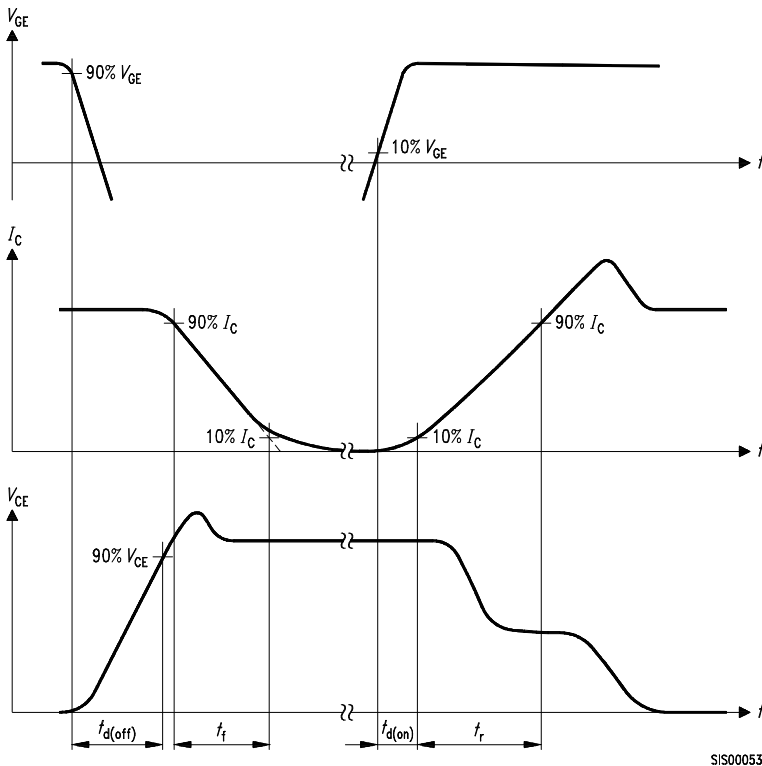
DOCUMENT NO.  
Z8B00003327

SCALE

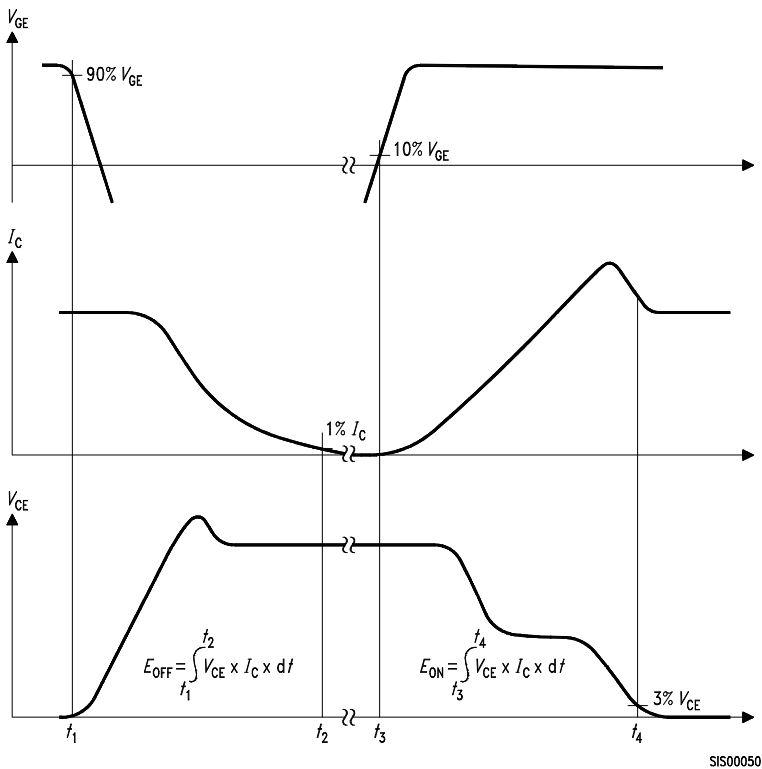
EUROPEAN PROJECTION

ISSUE DATE  
09-07-2010

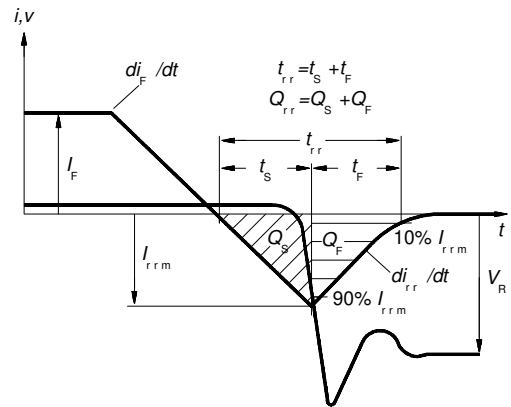
REVISION  
05



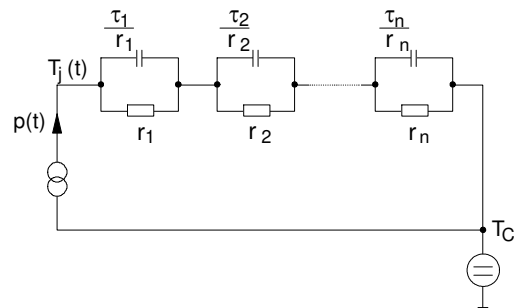
**Figure A. Definition of switching times**



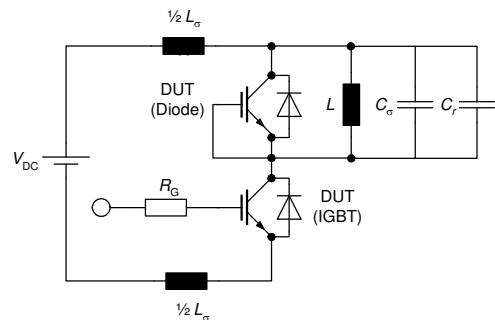
**Figure B. Definition of switching losses**



**Figure C. Definition of diodes switching characteristics**



**Figure D. Thermal equivalent circuit**



**Figure E. Dynamic test circuit**  
Leakage inductance  $L_{\sigma} = 180\text{nH}$ ,  
Stray capacitor  $C_{\sigma} = 40\text{pF}$ ,  
Relief capacitor  $C_r = 4\text{nF}$  (only for ZVT switching)

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For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office ([www.infineon.com](http://www.infineon.com)).

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